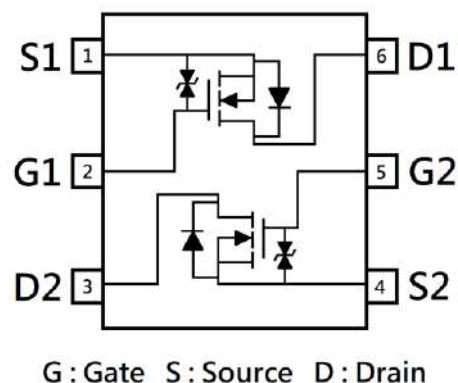
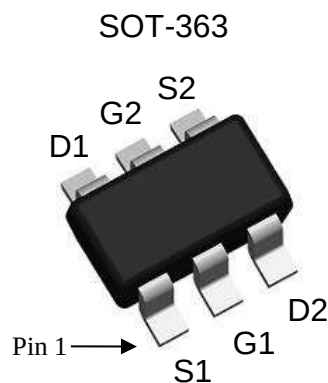


Dual N- Channel Enhancement Mode Power MOSFET

Features :

- Low On Resistance
- Low Gate Charge
- RoHS compliant package
- ESD protected gate



BV_{DSS}	20V
$I_D @ V_{GS}=4.5V, T_A=25^\circ C$	1.8A
$R_{DS(ON)} \text{ typ. } @ V_{GS}=4.5V, I_D=1A$	90m Ω
$R_{DS(ON)} \text{ typ. } @ V_{GS}=2.5V, I_D=1A$	105m Ω
$R_{DS(ON)} \text{ typ. } @ V_{GS}=1.8V, I_D=0.5A$	125m Ω

Ordering Information

Device	Package	Shipping
KWA080A02KE	SOT-363 (Pb-free lead plating and halogen-free package)	3000 pcs / Tape & Reel

Absolute Maximum Ratings (T_A=25°C)

Parameter		Symbol	Limits	Unit
Drain-Source Voltage		V _{DS}	20	V
Gate-Source Voltage		V _{GS}	±8	
Continuous Drain Current @ V _{GS} =4.5V, T _A =25°C		I _D	1.8	A
Continuous Drain Current @ V _{GS} =4.5V, T _A =70°C			1.4	
Pulsed Drain Current *a		I _{DM}	7	
Continuous Body Diode Forward Current @ T _A =25°C		I _S	0.4	
ESD susceptibility *b		V _{ESD}	1000	V
Total Power Dissipation	T _A =25°C	P _D	0.5	W
	T _A =70°C		0.3	
Operating Junction and Storage Temperature Range		T _J , T _{stg}	-55~+150	°C

Thermal Data

Parameter	Symbol	Steady State	Unit
Thermal Resistance, Junction-to-ambient	R _{θJA}	250	°C/W

Note:

*a. Repetitive rating, pulse width limited by junction temperature T_J(MAX)=150°C. Ratings are based on low frequency and low duty cycles to keep initial T_J=25°C.

*b. Human body model, 1.5kΩ in series with 100pF.

Electrical Characteristics (T_A=25°C, unless otherwise specified)

Symbol	Min.	Typ.	Max.	Unit	Test Conditions
Static					
BV _{DSS}	20	-	-	V	V _{GS} =0V, I _D =250μA
V _{GS(th)}	0.3	-	1		V _{DS} =V _{GS} , I _D =250μA
G _{FS}	-	3	-	S	V _{DS} =5V, I _D =1A
I _{GSS}	-	-	±10	μA	V _{GS} =±8V, V _{DS} =0V
I _{DSS}	-	-	1		V _{DS} =16V, V _{GS} =0V
R _{DS(ON)}	-	90	125	mΩ	V _{GS} =4.5V, I _D =1A
	-	105	150		V _{GS} =2.5V, I _D =1A
	-	125	250		V _{GS} =1.8V, I _D =0.5A
Dynamic					
C _{iss}	-	137	-	pF	V _{DS} =10V, V _{GS} =0V, f=1MHz
C _{oss}	-	32	-		
C _{rss}	-	25	-		
R _g	-	12	-	Ω	f=1MHz
Q _g *1, 2	-	2.3	-	nC	V _{DS} =16V, I _D =1A, V _{GS} =4.5V
Q _{gs} *1, 2	-	0.7	-		
Q _{gd} *1, 2	-	0.1	-		
t _{d(ON)} *1, 2	-	3.7	-	ns	V _{DS} =10V, I _D =1A, V _{GS} =4.5V, R _{GS} =10Ω
t _r *1, 2	-	17	-		
t _{d(OFF)} *1, 2	-	18	-		
t _f *1, 2	-	8.2	-		
Source-Drain Diode					
V _{SD} *1	-	0.84	1.2	V	I _S =1A, V _{GS} =0V
t _{rr}	-	4.2	-	ns	I _F =1A, dI _F /dt=100A/μs
Q _{rr}	-	1.1	-	nC	

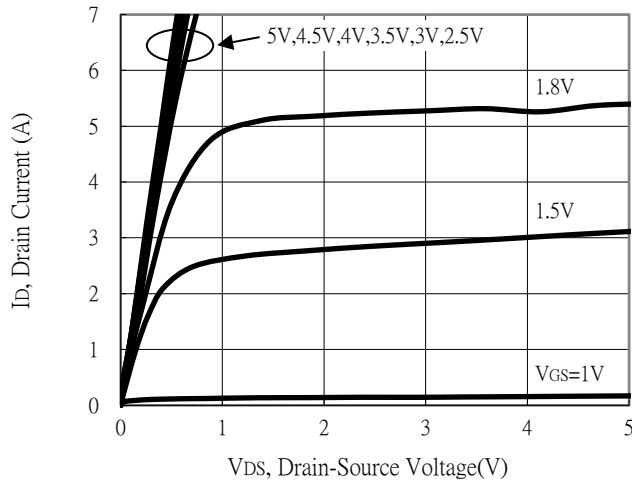
Note:

*1. Pulse Test : Pulse Width ≤300μs, Duty Cycle≤2%

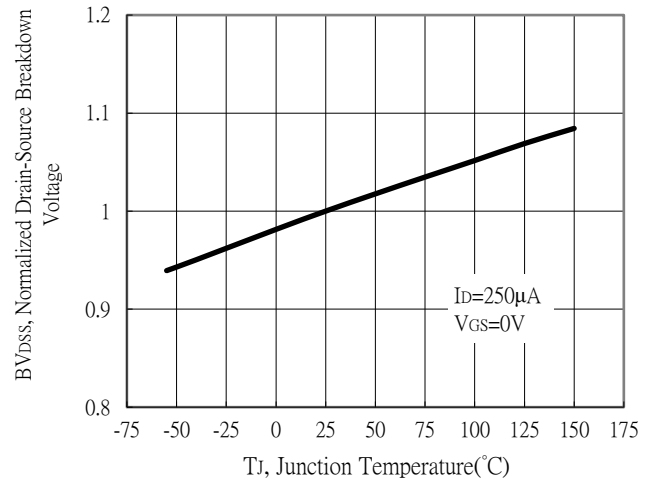
*2. Independent of operating temperature

Typical Characteristics

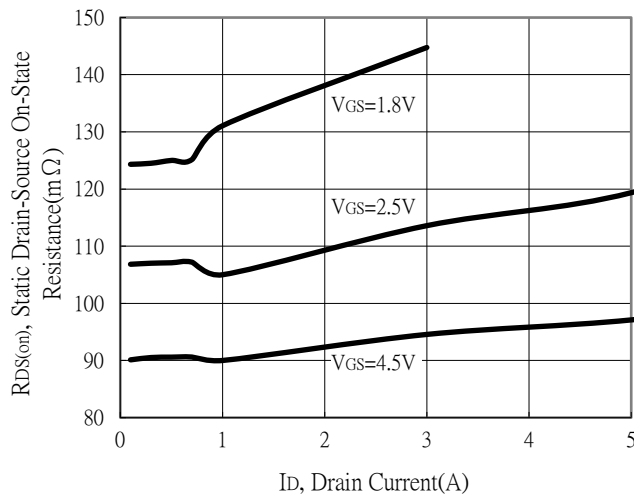
Typical Output Characteristics



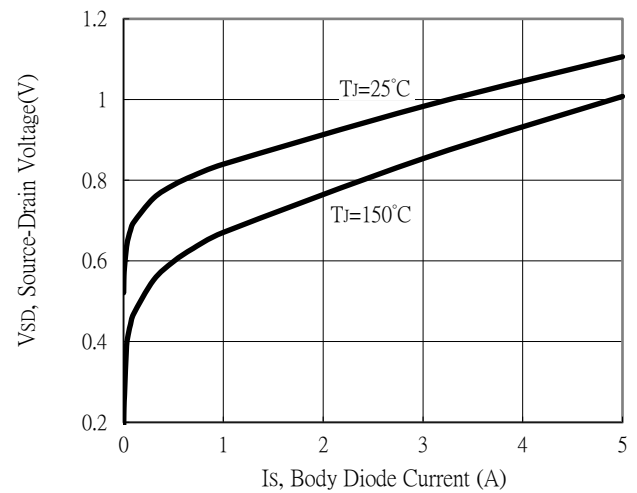
Breakdown Voltage vs Ambient Temperature



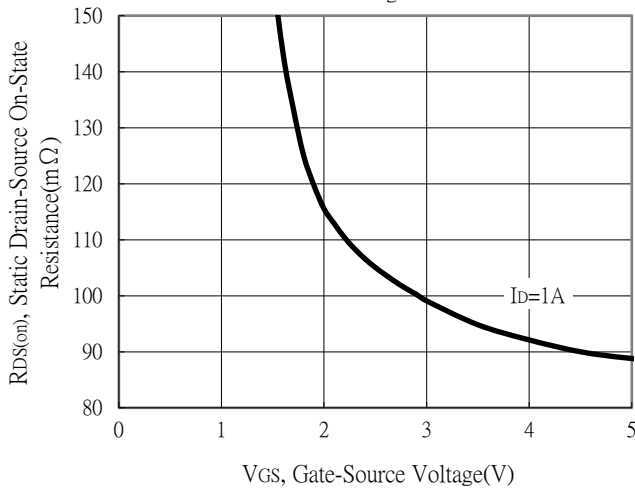
Static Drain-Source On-State resistance vs Drain Current



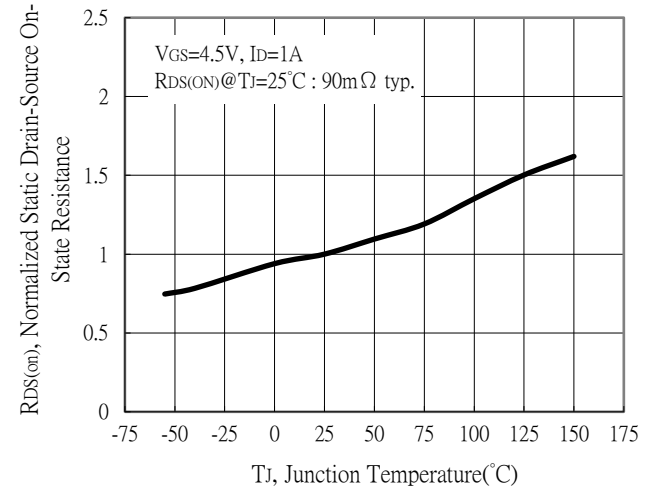
Body Diode Current vs Source-Drain Voltage



Static Drain-Source On-State Resistance vs Gate-Source Voltage

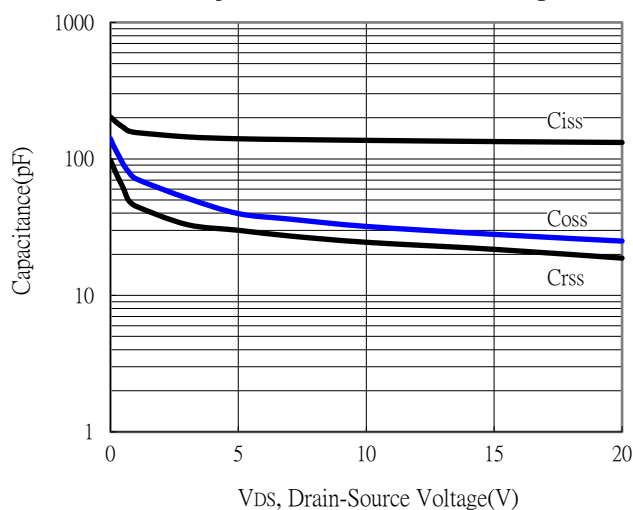


Drain-Source On-State Resistance vs Junction Temperature

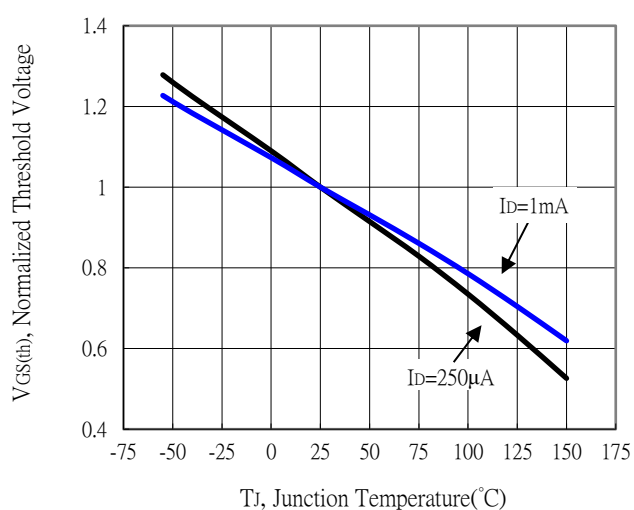


Typical Characteristics (Cont.)

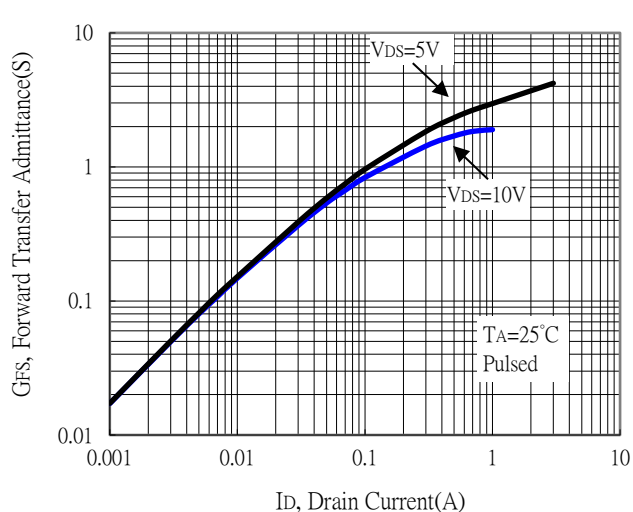
Capacitance vs Drain-to-Source Voltage



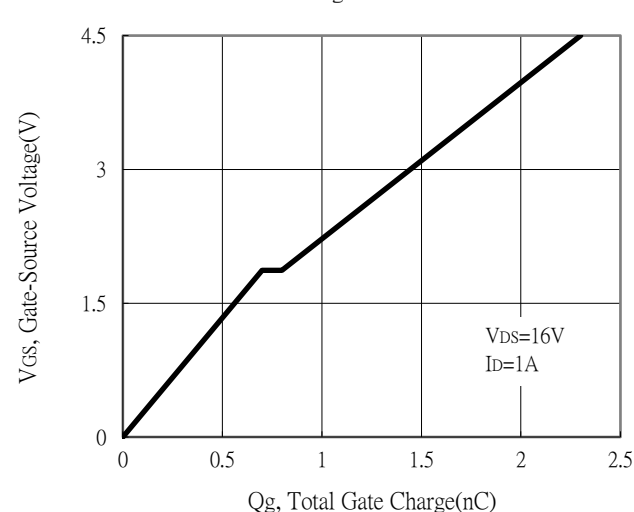
Threshold Voltage vs Junction Temperature



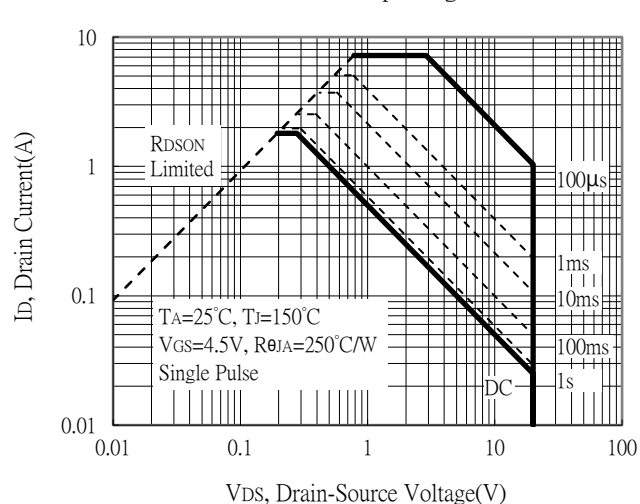
Forward Transfer Admittance vs Drain Current



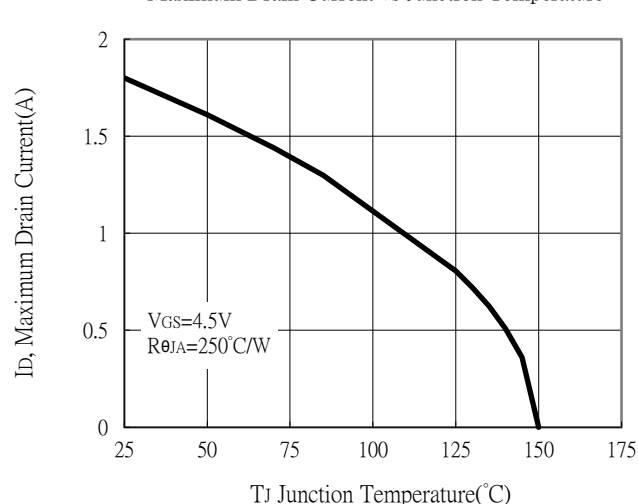
Gate Charge Characteristics



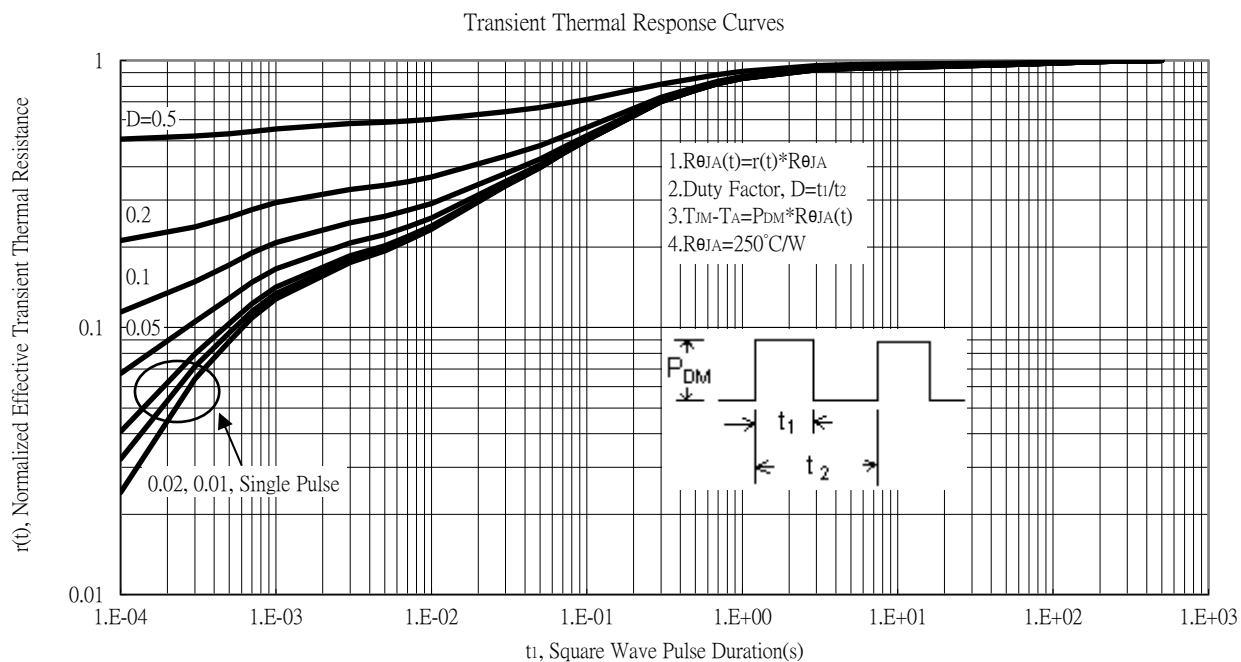
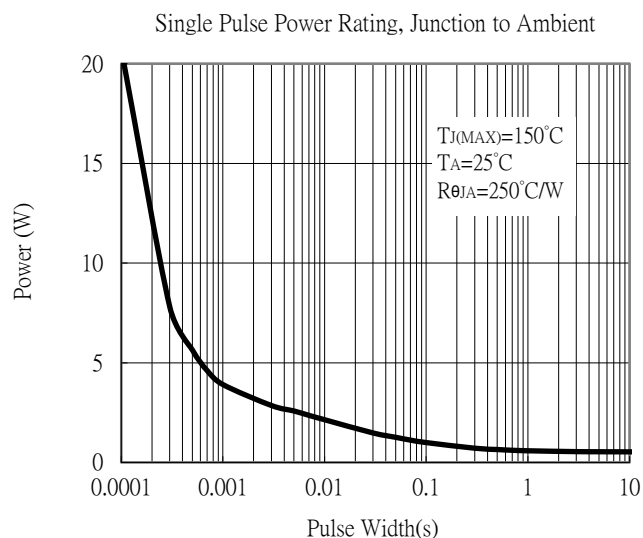
Maximum Safe Operating Area



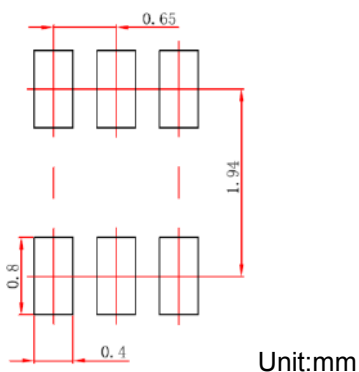
Maximum Drain Current vs Junction Temperature



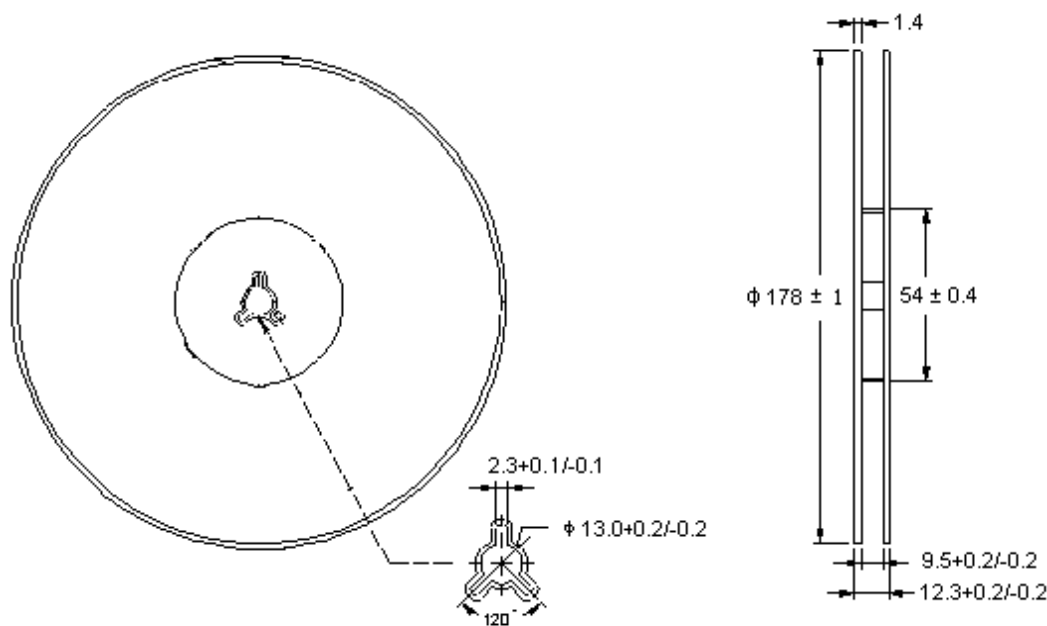
Typical Characteristics (Cont.)



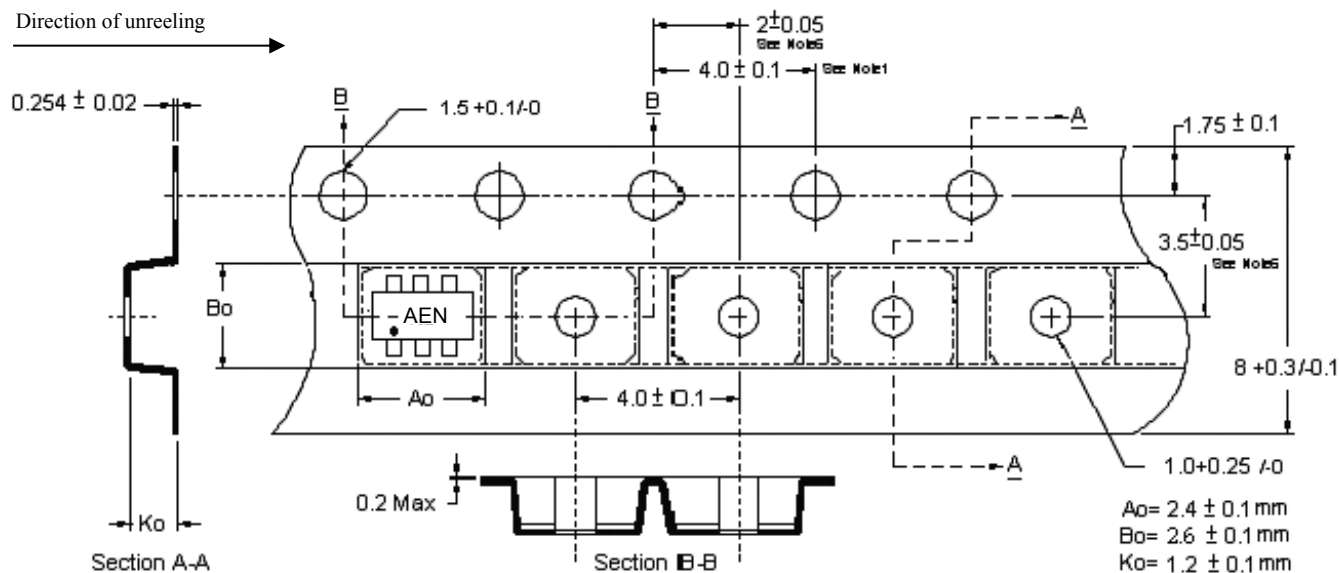
Recommended Soldering Footprint



Reel Dimension



Carrier Tape Dimension

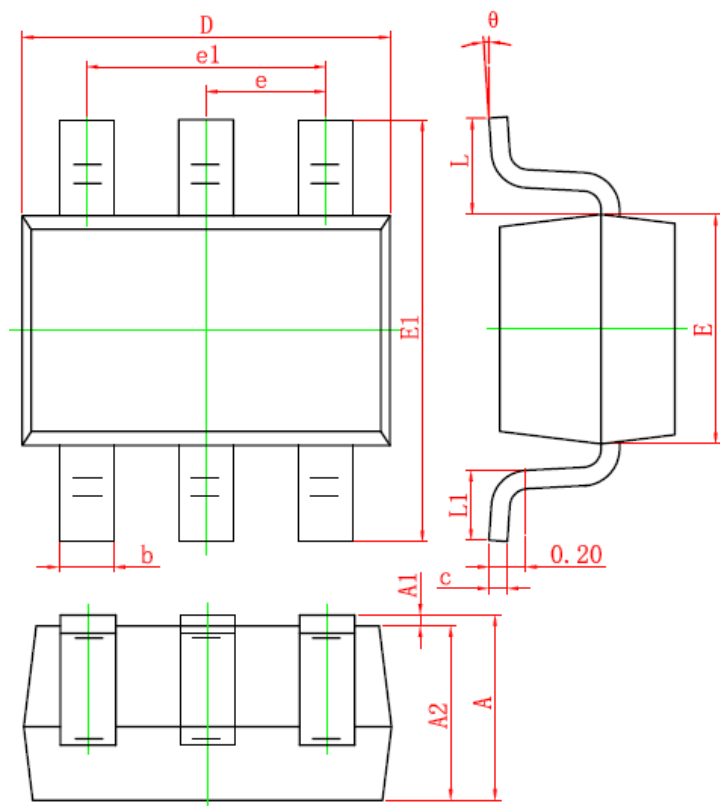


Notes

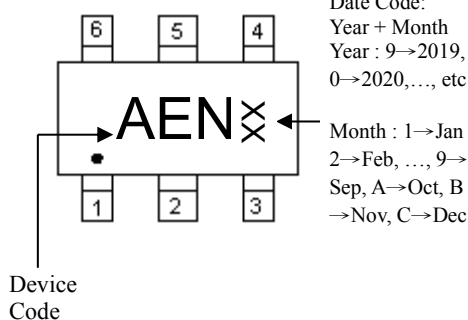
1. 10 sprocket hole pitch cumulative tolerance ± 0.2 .
2. Camber not to exceed 1mm in 100mm.
3. Material: Conductive Black Polystyrene.
4. A_0 & B_0 measured on a plane 0.3mm above the bottom of the pocket.
5. K_0 measured from a plane on the inside bottom of the pocket to the top surface of the carrier.
6. Pocket position relative to sprocket hole measured as true position of pocket, not pocket hole.

Unit : millimeter

SOT-363 Dimension



Marking:



6-Lead SOT-363 Plastic
Surface Mounted Package

Style:

- Pin 1. Source1 (S1)
- Pin 2. Gate1 (G1)
- Pin 3. Drain2 (D2)
- Pin 4. Source2 (S2)
- Pin 5. Gate2 (G2)
- Pin 6. Drain1 (D1)

DIM	Millimeters		Inches		DIM	Millimeters		Inches	
	Min.	Max.	Min.	Max.		Min.	Max.	Min.	Max.
A	0.900	1.100	0.035	0.043	E1	2.150	2.450	0.085	0.096
A1	0.000	0.100	0.000	0.004	e	0.650	TYP	0.026	TYP
A2	0.900	1.000	0.035	0.039	e1	1.200	1.400	0.047	0.055
b	0.150	0.350	0.006	0.014	L	0.525	REF	0.021	REF
c	0.080	0.150	0.003	0.006	L1	0.260	0.460	0.010	0.018
D	2.000	2.200	0.079	0.087	θ	0°	8°	0°	8°
E	1.150	1.350	0.045	0.053					